

Title (en)  
IC COMPONENT COMPRISING A COOLING ARRANGEMENT

Title (de)  
IC-BAUELEMENT MIT KÜHLANORDNUNG

Title (fr)  
COMPOSANT DE CIRCUIT INTEGRE DOTE D'UN SYSTEME DE REFROIDISSEMENT

Publication  
**EP 1938373 A2 20080702 (DE)**

Application  
**EP 06793022 A 20060825**

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Abstract (en)  
[origin: WO2007045520A2] The invention relates to an IC component (2) comprising a cooling arrangement (1) which is embodied as an electronic housing provided with a cooling body (7). According to the invention, the IC component (2) is directly arranged on the cooling body (7) in the electronic housing. The invention advantageously provides a cooling arrangement (1) for IC components (2) that enables the IC component (2) to be efficiently and directly cooled and assembled in a simple manner, without requiring additional components. It is especially suitable for applications in electronic housings in the automobile industry.

IPC 8 full level  
**H01L 23/367** (2006.01)

CPC (source: EP US)  
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